ABSTRACT OF THE DISCLOSURE

An objective of this invention is to provide an epoxy resin composition for encapsulating a semiconductor chip, which has good flowability without deterioration in curability. Specifically, this invention provides a resin composition for encapsulating a semiconductor chip containing a phenol aralkyl type epoxy resin containing biphenylene structure (A), a phenol aralkyl type resin containing phenylene or biphenylene structure (B), an inorganic filler (C) in 84 wt% to 90 wt% both inclusive of the total amount of the epoxy resin composition and a curing accelerator (D) as main components, comprising a silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive of the total amount of the epoxy resin composition and Compound (F) contains two or more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring in more than or equal to 0.01 wt% of the total amount of the epoxy resin composition.